





Applicable standard					
Rating	Operating temperature range	-35 °C to +85 °C(Note 1)	Storage temperature range	-10 °C to +60 °C(Note 3)	
	Operating humidity range	20 % to 80 % (Note 2)	Storage humidity range	40 % to 70 %(Note 3)	
	Voltage	150 V AC(DC)	APPLICABLE CONTACT	DF14- * S-1.25C	
	Current	1 A			
Specifications					
Item		Test method	Requirements	QT	AT
Construction					
General examination		Visually and by measuring instrument.	According to drawing.	X	X
Marking		Confirmed visually.		X	X
Electric characteristics					
Contact resistance		20 mV MAX, 1 mA (DC or 1000 Hz). 	30 mΩ MAX.	X	—
Insulation resistance		100 V DC.	500 MΩ MIN.	X	—
Voltage proof		500 V AC for 1 min.	No flashover or breakdown.	X	—
Mechanical characteristics					
Mechanical operation		30 times insertions and extractions.	1) Contact resistance: 30 mΩ MAX. 2) No damage, crack or looseness of parts.	X	—
Vibration		Frequency 10 to 55 Hz, single amplitude 0.75 mm, at 2 h, for 3 directions.	1) No electrical discontinuity of 1 μs. 2) No damage, crack or looseness of parts.	X	—
Shock		490 m/s ² duration of pulse 11 ms at 3 times for 3 directions.		X	—
Environmental characteristics					
Rapid change of temperature		Temperature -55→ 5 to 35→+85→ 5 to 35 °C Time 30→ 10 to 15 → 30→ 10 to 15 min Under 5 cycles.	1) Contact resistance: 30 mΩ MAX. 2) Insulation resistance: 500 MΩ MIN. 3) No damage, crack or looseness of parts.	X	—
Damp heat (steady state)		Exposed at 40±2 °C, 90 to 95 %, 96 h.		X	—
Resistance to soldering heat		1) Reflow soldering «Reflow area» Max250 °C within 10 sec Min 230 °C within 60 sec «Preheating area» 170 °C to 190 °C 60 sec to 120 sec put through in reflow furnace twice leave in ambient temperature and humidity for 1 hour. Connector temperature to be ambient for second reflow. 2) Manual soldering Soldering iron temperature: 350±5 °C, Soldering time: 5±1 sec. No strength on contact.	No deformation of case or excessive looseness of the terminals.	X	—
Solderability		Soldered at solder temperature, 235±5 °C for insertion duration, 3 sec.	Solder shall cover a minimum of 95 % of the surface being immersed.	X	—
Remarks Note 1: Include the temperature rising by current. Note 2: No condensing Note 3: Apply to the condition of long term storage for unused products before mounted on PCB. After mounted on PCB board, operating temperature and humidity range is applied for interim storage during transportation.					
	Count	Description of revisions	Designed	Checked	Date
	1	DIS-H-00004206	HK. HAYASHI	SZ. ONO	18.09.12
Unless otherwise specified, refer to IEC 60512.			Approved	HS.OKAWA	18.04.03
			Checked	TS.FUKUSHIMA	18.04.03
			Designed	TS.KUMAZAWA	18.04.03
			Drawn	MK.INOUE	18.04.02
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			Drawing no.		ELC-160309-24-00
	Specification sheet		Part no.	DF14A-*P-1.25H(24)	
	Hirose electric co., Ltd.		Code no.	CL538	 1/1